



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Nguyen et al.

Attorney Docket No.: NSC1P131X1

Application No.: 10/080,913

Examiner: Not Yet Assigned

Filed: February 21, 2002

Group: Unknown

Title: METHOD AND APPARATUS FOR
FORMING AN UNDERFILL ADHESIVE LAYER

#3/a
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Payton

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Commissioner for Patents, Washington, DC 20231 on March 25, 2002.

Signed: _____

Laura M. Dean

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Before examination of the subject patent application, please amend the above-identified patent application as follows:

In the Specification:

Please **replace** original paragraph [0007] with the following **amended** paragraph [0007]:

a1
To achieve the foregoing and other objects and in accordance with the purpose of the present invention, an apparatus and method for forming a layer of underfill adhesive on an integrated circuit in wafer form is disclosed. In one embodiment, the layer of underfill adhesive is disposed and partially cured on the active surface of the wafer. Once the underfill adhesive has been partially cured, the wafer is signulated. The individual integrated circuits or die are then mounted onto a substrate such as a printed circuit board. When the solder balls of the integrated circuit are reflowed to form joints with corresponding contact pads on the substrate, the underfill adhesive is completely cured. In an alternative embodiment, the underfill adhesive is fully cured after it is disposed onto the active surface of the wafer. In various other embodiments, the underflow adhesive is disposed onto the wafer using stencil printing, screen printing, molding, or